STRUCTURE Silicon monolithic integrated circuits

PRODUCT SERIES Bipolar stepping motor driver

TYPE **BD63843EFV**

FUNCTION
- PWM constant current controllable two H bridge driver
- Built-in translator circuit for CLK-IN control
- Full, Half, Eighth, and Sixteenth step modes
- Mix decay control

○Absolute maximum ratings(Ta=25°C)

Item	Symbol	Ratings	Unit
Supply voltage	$V_{CC1,2}$	-0.3～+36.0	V
Power dissipation	Pd	1.45※1	W
		4.70※2	W
Input voltage for control pin	V_{IN}	-0.3～+7.0	V
RNF voltage	V_{RNF}	0.7	V
Output current	I_{OUT}	1.0※3	A/phase
Output current(peak)※4	$I_{OUTPEAK}$	1.5※3	A/phase
Operating temperature range	T_{opr}	-25～+85	°C
Storage temperature range	T_{stg}	-55～+150	°C
Junction temperature	T_{jmax}	+150	°C

※1 70mm×70mm×1.6mm glass epoxy board. Derating in done at 11.6mW/°C for operating above Ta=25°C.
※2 4-layer recommended board. Derating in done at 37.6mW/°C for operating above Ta=25°C.
※3 Do not, however exceed Pd, ASO and Tjmax=150°C.
※4 Pulse width tw≦1ms, duty 20%.

○Operating conditions (Ta=-25～+85°C)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	$V_{CC1,2}$	19	24	28	V
Input voltage for control pin	V_{IN}	0	-	5.5	V
Output current	I_{OUT}	-	0.5	0.7※5	A/phase

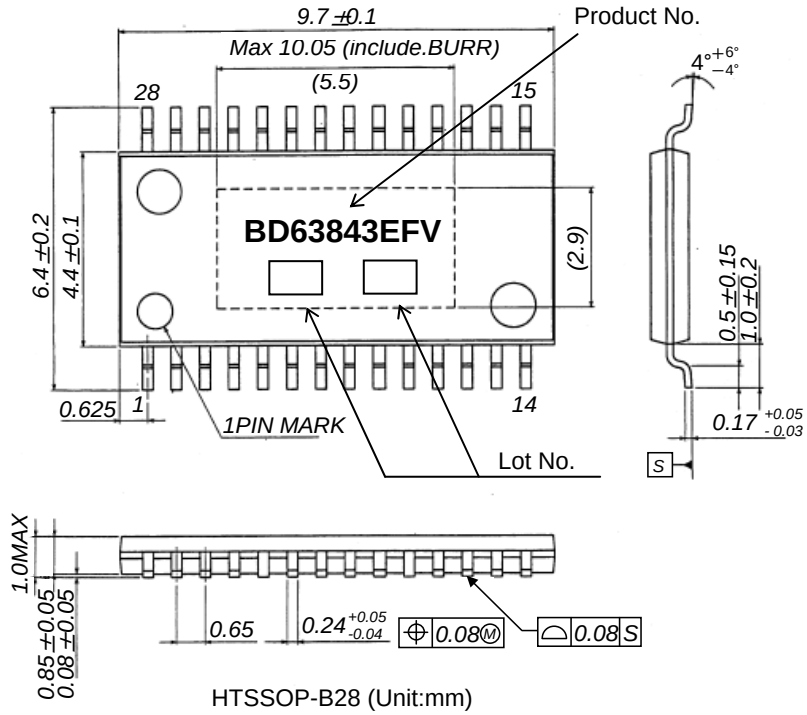
※5 Do not, however exceed Pd, ASO.

This product isn't designed for protection against radioactive rays.

○Electrical characteristics (Unless otherwise specified, Ta=25°C, $V_{CC1,2}$=24V)

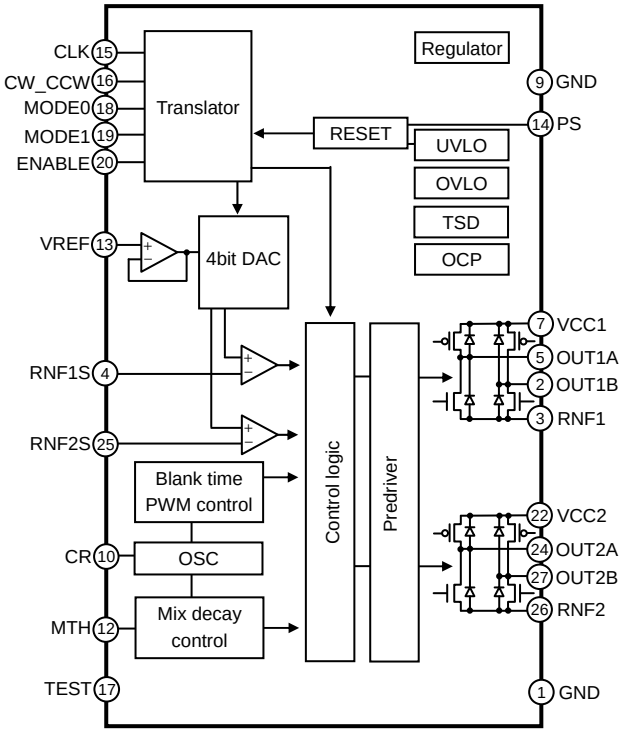
Item	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Whole						
Circuit current at standby	I_{CCST}	-	1.0	2.5	mA	PS=L
Circuit current	I_{CC}	-	2.5	5.0	mA	PS=H, VREF=3V
Control input (CLK, CW_CCW, MODE0, MODE1, ENABLE, PS)						
H level input voltage	V_{INH}	2.0	-	-	V	
L level input voltage	V_{INL}	-	-	0.8	V	
H level input current	I_{INH}	35	50	100	μA	V_{IN}=5V
L level input current	I_{INL}	-10	0	-	μA	V_{IN}=0V
Output (OUT1A, OUT1B, OUT2A, OUT2B)						
Output ON resistance	R_{ON}	-	1.90	2.47	Ω	I_{OUT}=0.5A, Sum of upper and lower
Output leak current	I_{LEAK}	-	-	10	μA	
Current control						
RNFXS input current	I_{RNFS}	-2.0	-0.1	-	μA	RNFXS=0V
RNFX input current	I_{RNF}	-40	-20	-	μA	RNFX=0V
VREF input current	I_{VREF}	-2.0	-0.1	-	μA	VREF=0V
VREF input voltage range	V_{REF}	0	-	3.0	V	
MTH input current	I_{MTH}	-2.0	-0.1	-	μA	MTH=0V
MTH input voltage range	V_{MTH}	0	-	3.5	V	
Minimum on time (Blank time)	t_{ONMIN}	0.3	0.8	1.5	μs	C=1000pF, R=39kΩ
Comparator threshold 1	V_{CTH1}	0.570	0.600	0.630	V	VREF=3V, 100%
Comparator threshold 2	V_{CTH2}	0.403	0.424	0.445	V	VREF=3V, 70.71%
Comparator threshold 3	V_{CTH3}	0.196	0.230	0.264	V	VREF=3V, 38.27%

○Package outline



HTSSOP-B28 (Unit:mm)

○Block diagram



○Pin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	GND	15	CLK
2	OUT1B	16	CW_CCW
3	RNF1	17	TEST
4	RNF1S	18	MODE0
5	OUT1A	19	MODE1
6	NC	20	ENABLE
7	VCC1	21	NC
8	NC	22	VCC2
9	GND	23	NC
10	CR	24	OUT2A
11	NC	25	RNF2S
12	MTH	26	RNF2
13	VREF	27	OUT2B
14	PS	28	NC

NC : Non Connection

○Operation Notes

(1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

(2) Power supply lines

As return of current regenerated by back EMF of motor happens, take steps such as putting capacitor between power supply and GND as an electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.

(3) GND potential

The potential of GND pin must be minimum potential in all operating conditions.

(4) Metal on the backside (Define the side where product markings are printed as front)

The metal on the backside is shorted with the backside of IC chip therefore it should be connected to GND. Be aware that there is a possibility of malfunction or destruction if it is shorted with any potential other than GND.

(5) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes the metal on the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.

(6) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

(7) ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

(8) Thermal shutdown circuit

The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes Tjmax=150°C, and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.

(9) Ground Wiring Pattern

When using both large current and small signal GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

(10) TEST pin

Be sure to connect TEST pin to GND.

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